US00D855580S

(12) **United States Design Patent**
Ma

(10) **Patent No.: US D855,580 S**
(45) **Date of Patent: ** Aug. 6, 2019**

(54) **EARPHONE**

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(72) Inventor: **Longhua Ma**, Shenzhen (CN)

(73) Assignee: **Shenzhen Lingyin Technology Co., Ltd.**, Shenzhen (CN)

(**) Term: **15 Years**

(21) Appl. No.: **29/636,046**

(22) Filed: **Feb. 6, 2018**

(51) **LOC (12) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/205**; D14/206

(58) **Field of Classification Search**
USPC D14/205, 223, 250, 206; 181/129, 130, 181/135; 379/430, 431; 381/380, 381, 381/370, 374; 455/90.3, 575.1, 569.1
CPC H04R 1/1066; H04R 1/1016; H04R 5/033; H04R 1/1033; H04R 25/00; H04R 1/10; H04R 1/105
See application file for complete search history.

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(Continued)

Primary Examiner — Paula Allen Greene

(57) **CLAIM**

The ornamental design for an earphone, as shown and described.

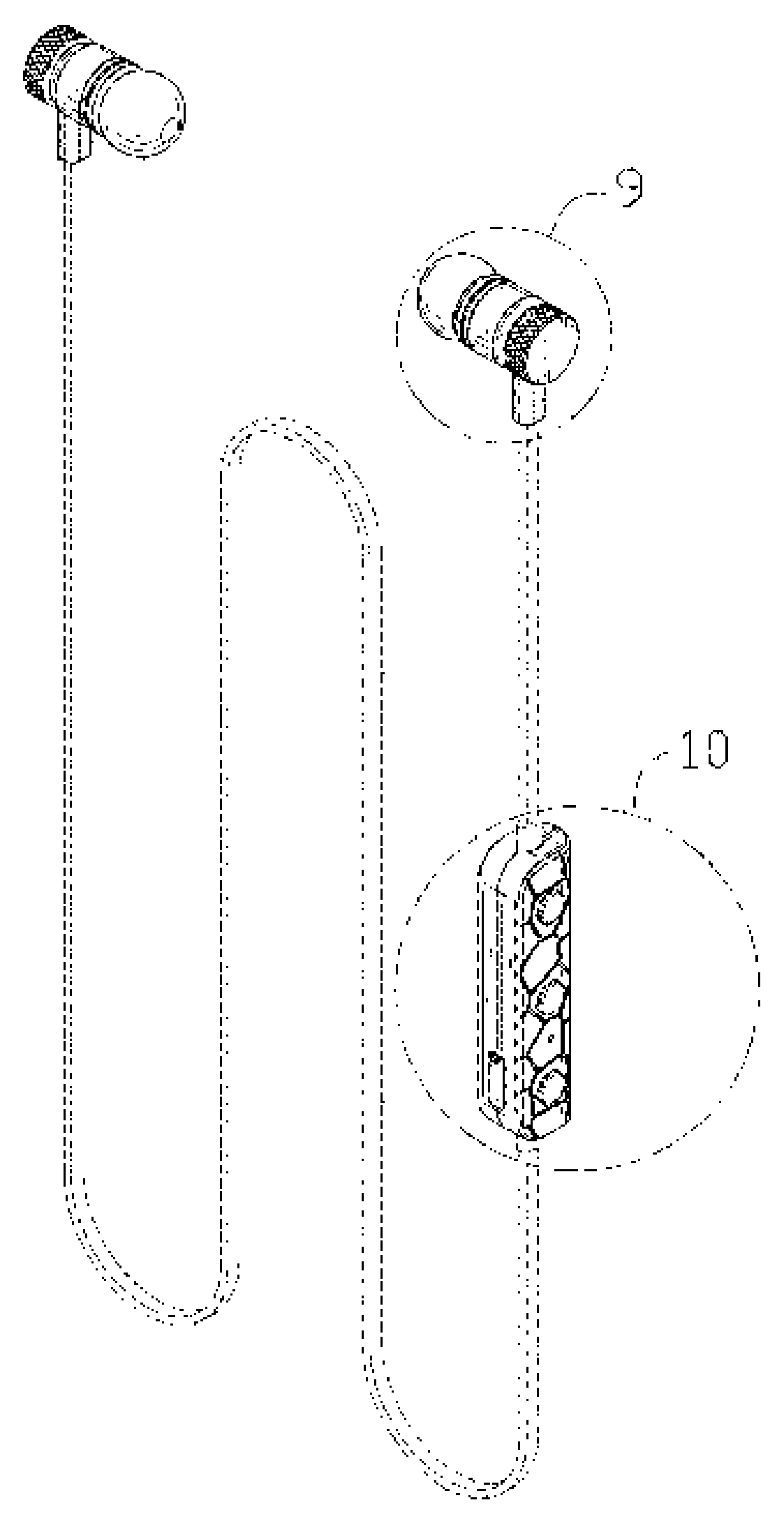
DESCRIPTION

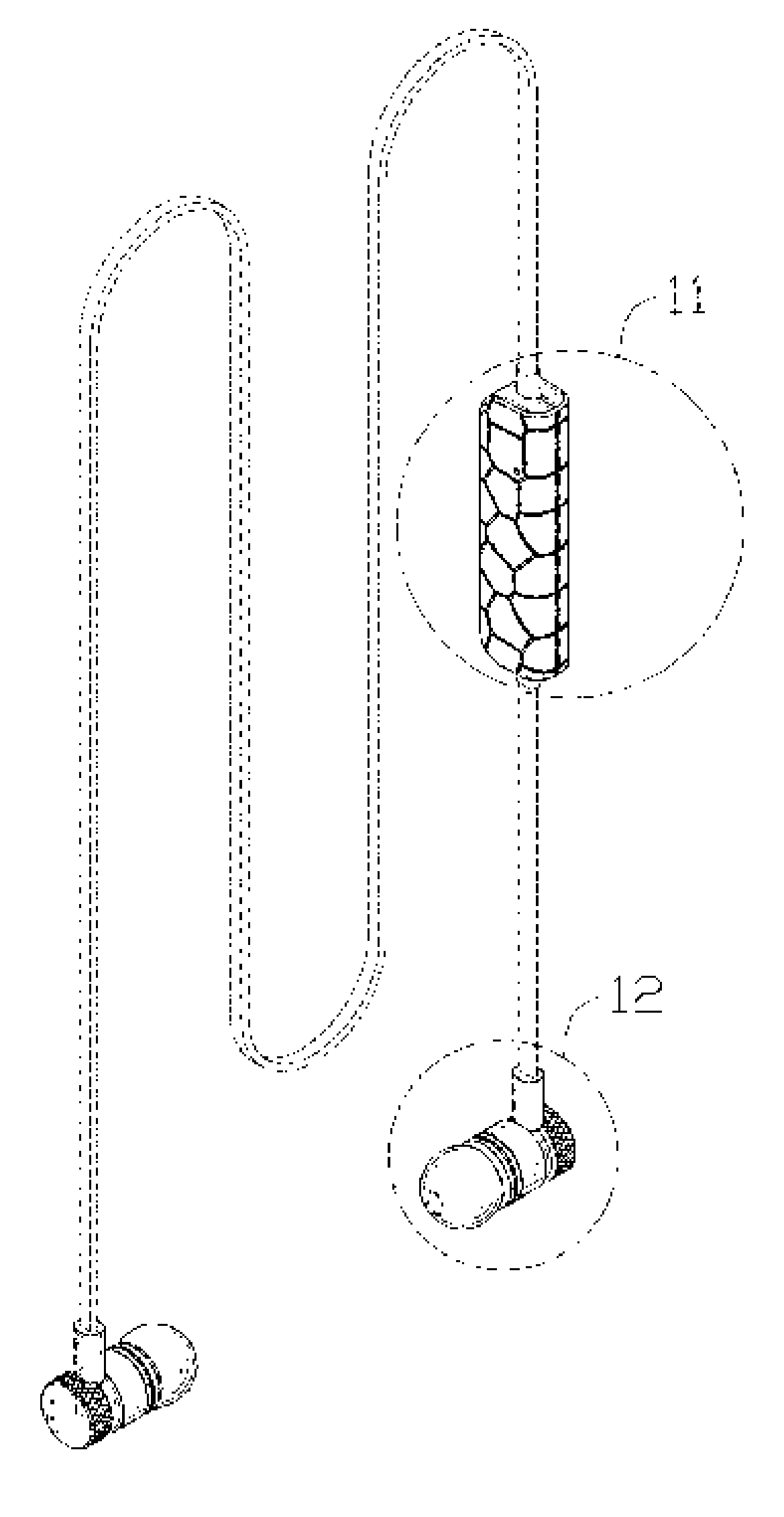
FIG. **1** is a top perspective view of an earphone showing my new design;
FIG. **2** is a bottom perspective view thereof;
FIG. **3** is a front elevational view thereof;
FIG. **4** is a rear elevational view thereof;
FIG. **5** is a left side elevational view thereof;
FIG. **6** is a right side elevational view thereof;
FIG. **7** is a top plan view thereof;
FIG. **8** is a bottom plan view thereof;
FIG. **9** is an enlarged view of the encircled portion **9** in FIG. **1**;
FIG. **10** is an enlarged view of the encircled portion **10** in FIG. **1**;
FIG. **11** is an enlarged view of the encircled portion **11** in FIG. **2**;
FIG. **12** is an enlarged view of the encircled portion **12** in FIG. **2**;
FIG. **13** is an enlarged view of the encircled portion **13** in FIG. **3**;
FIG. **14** is an enlarged view of the encircled portion **14** in FIG. **3**;
FIG. **15** is an enlarged view of the encircled portion **15** in FIG. **4**;
FIG. **16** is an enlarged view of the encircled portion **16** in FIG. **5**; and,
FIG. **17** is an enlarged view of the encircled portion **17** in FIG. **6**.

The broken lines are for the purpose of illustrating portions of the earphone that form no part of the claimed design.

The dot-dash broken lines encircling portions of the claimed design that are illustrated in enlargements form no part of the claimed design.

1 Claim, 17 Drawing Sheets





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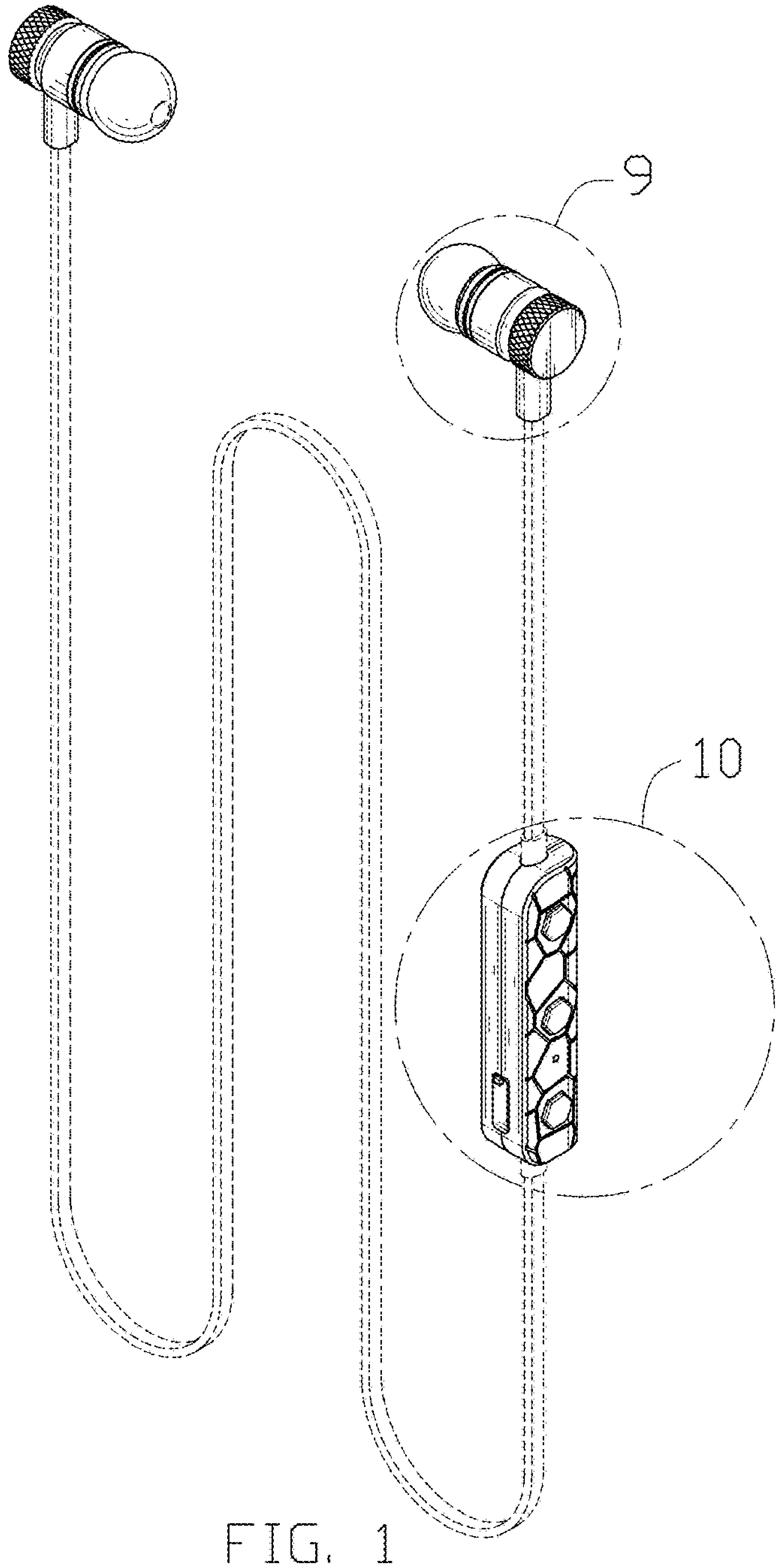


FIG. 1

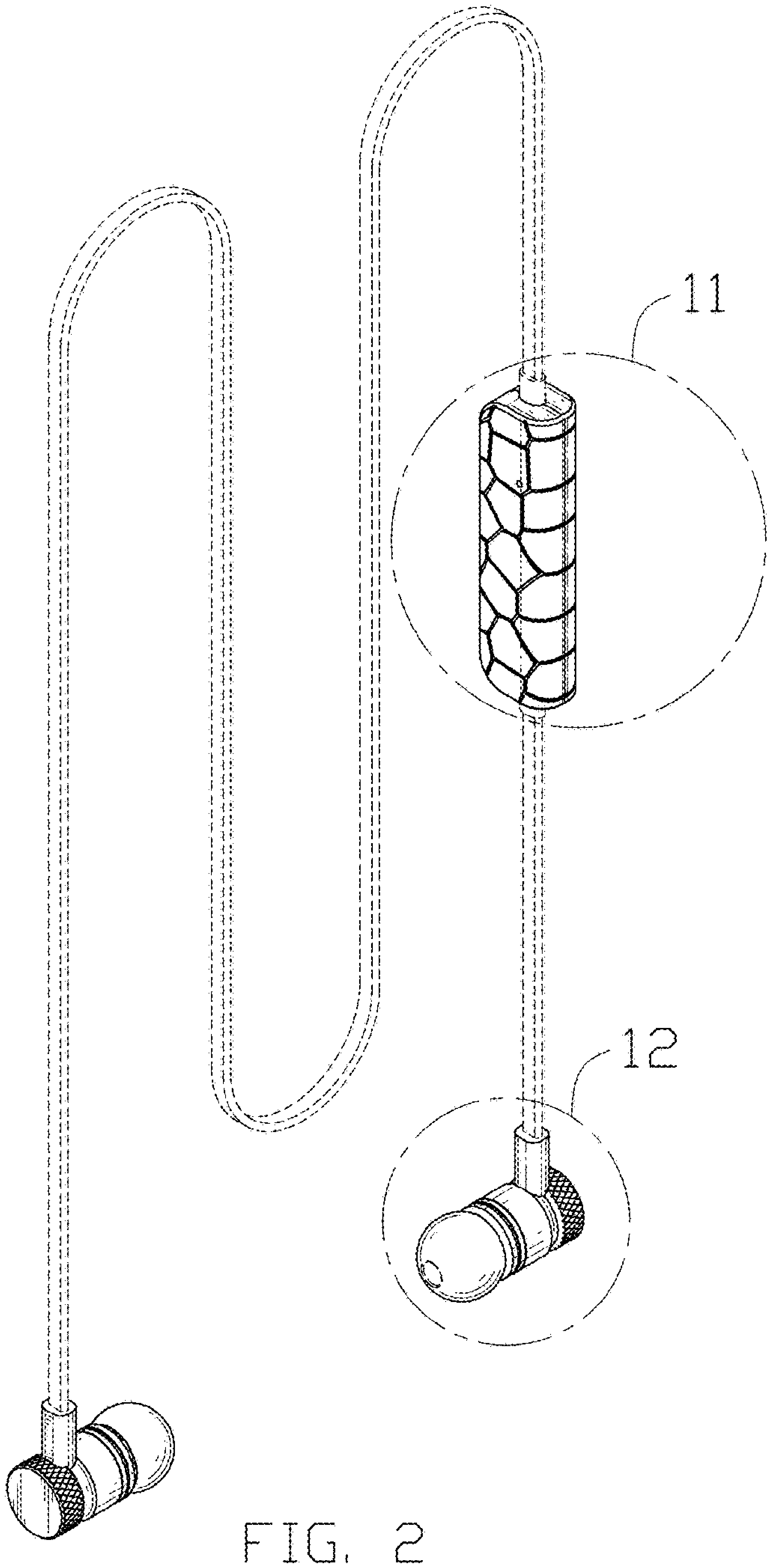


FIG. 2

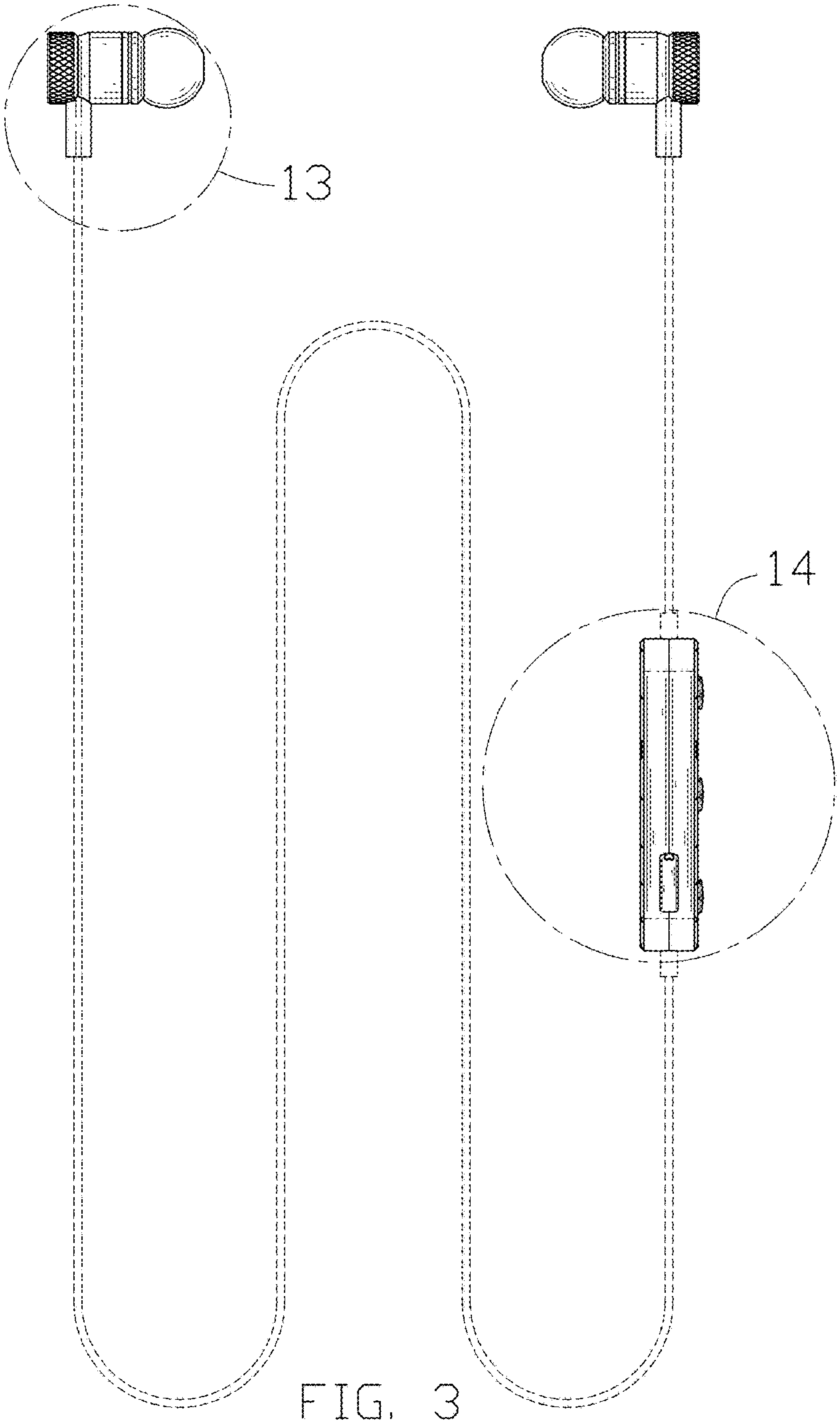
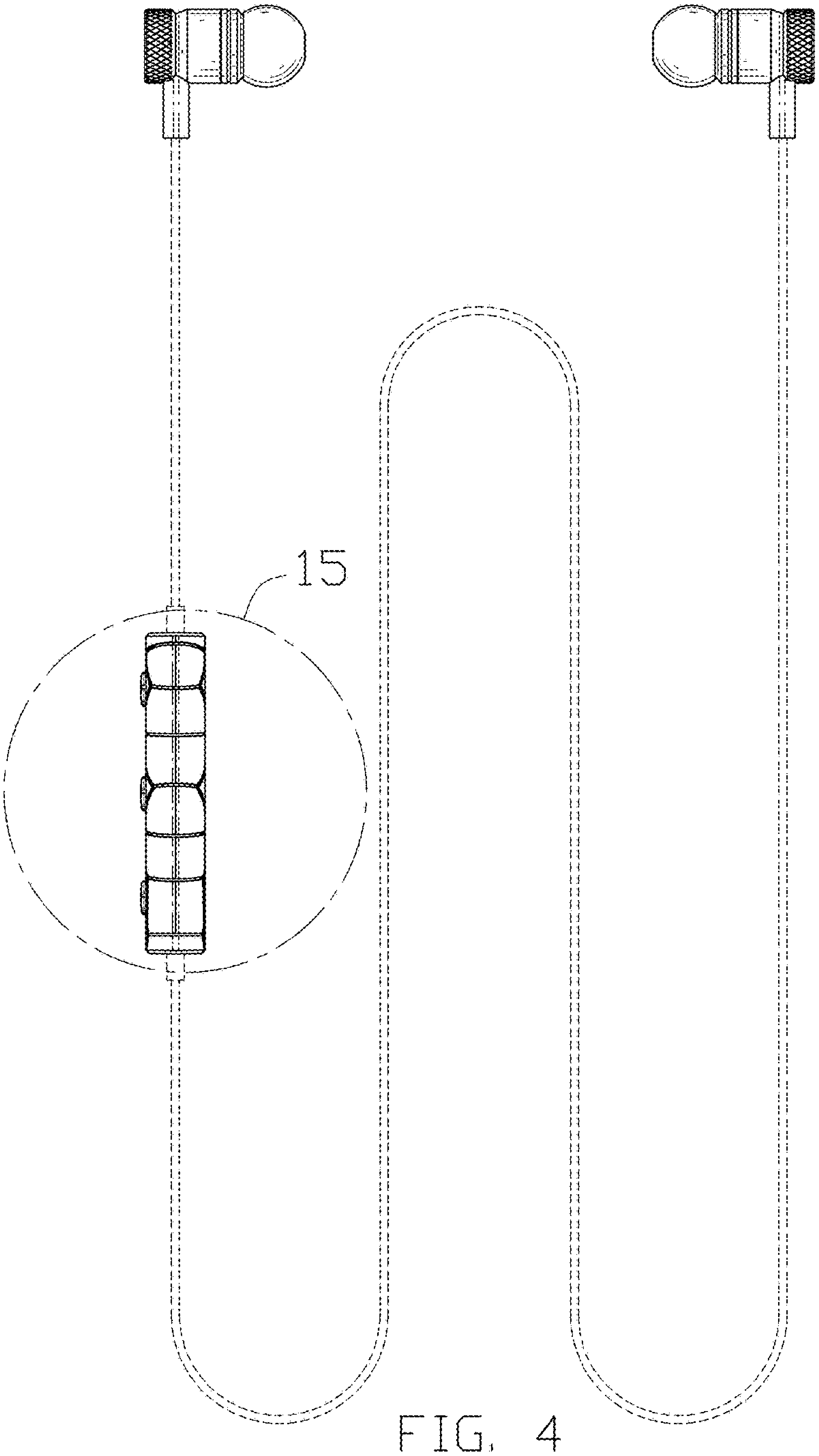


FIG. 3



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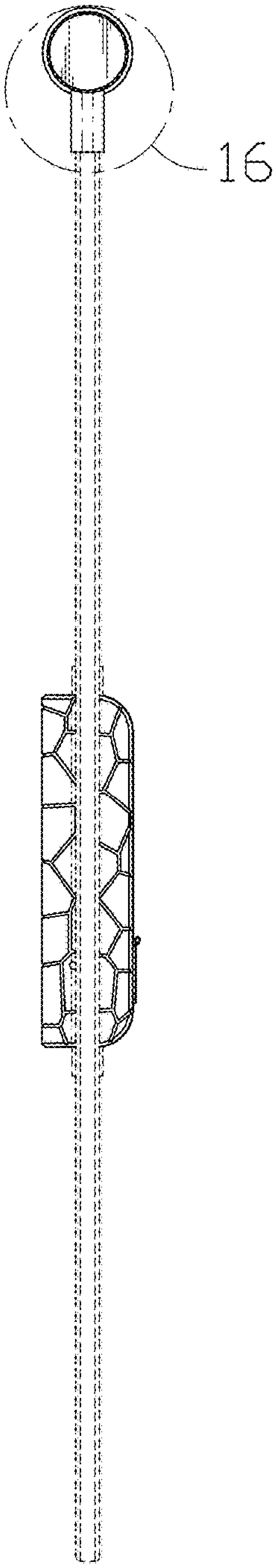


FIG. 5

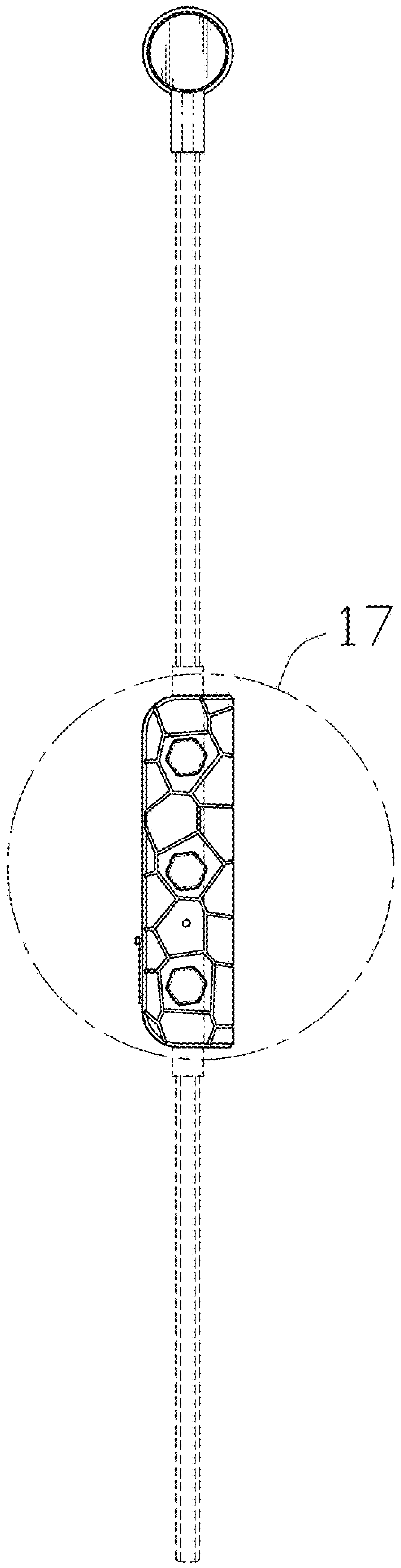


FIG. 6

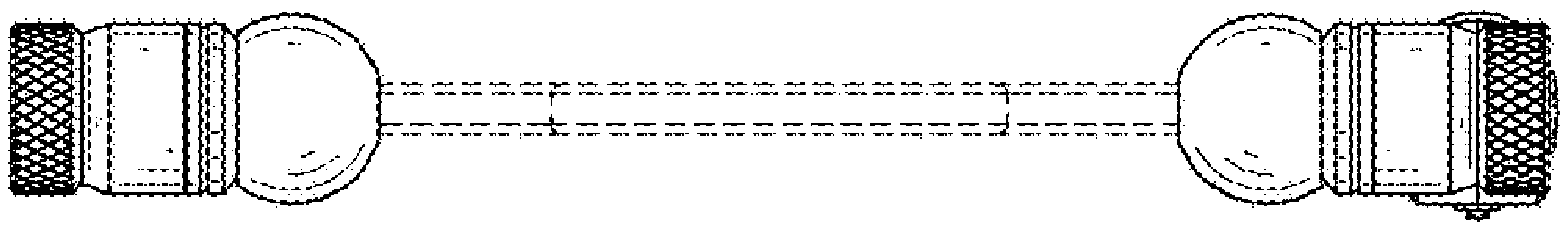


FIG. 7

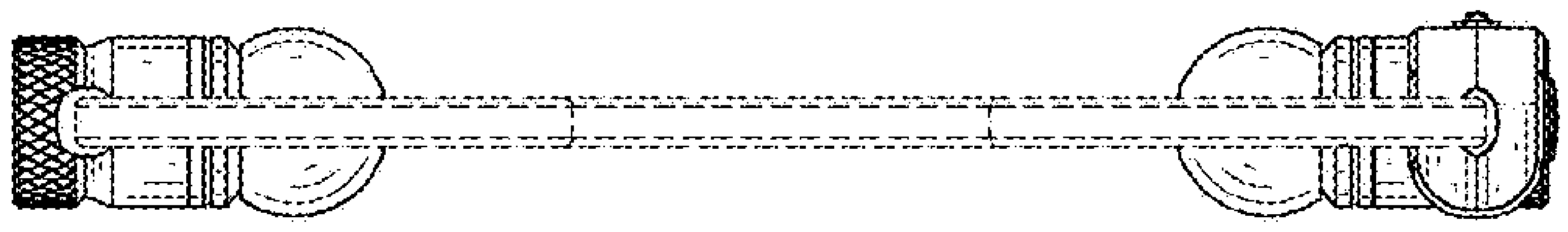
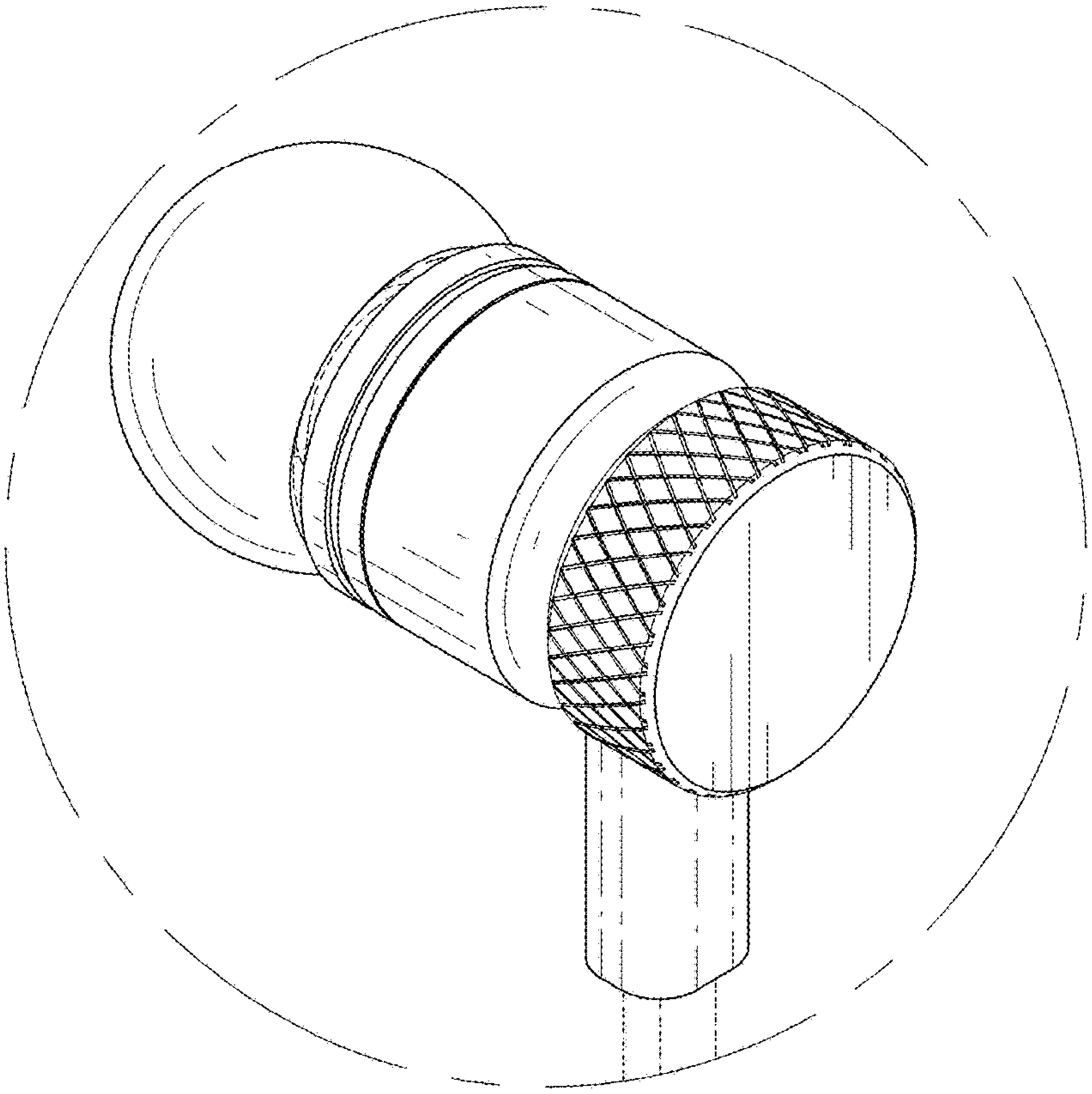


FIG. 8



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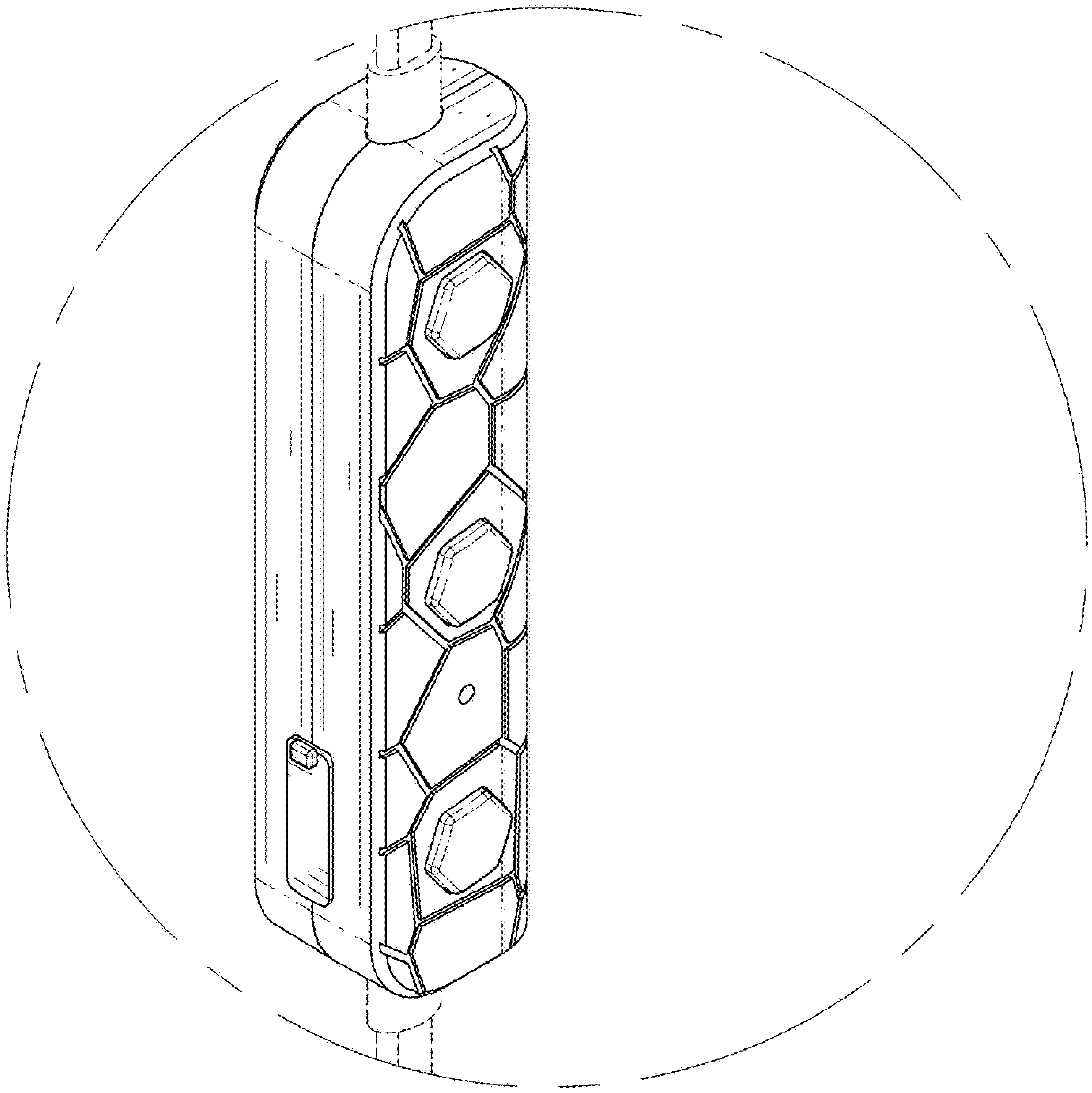

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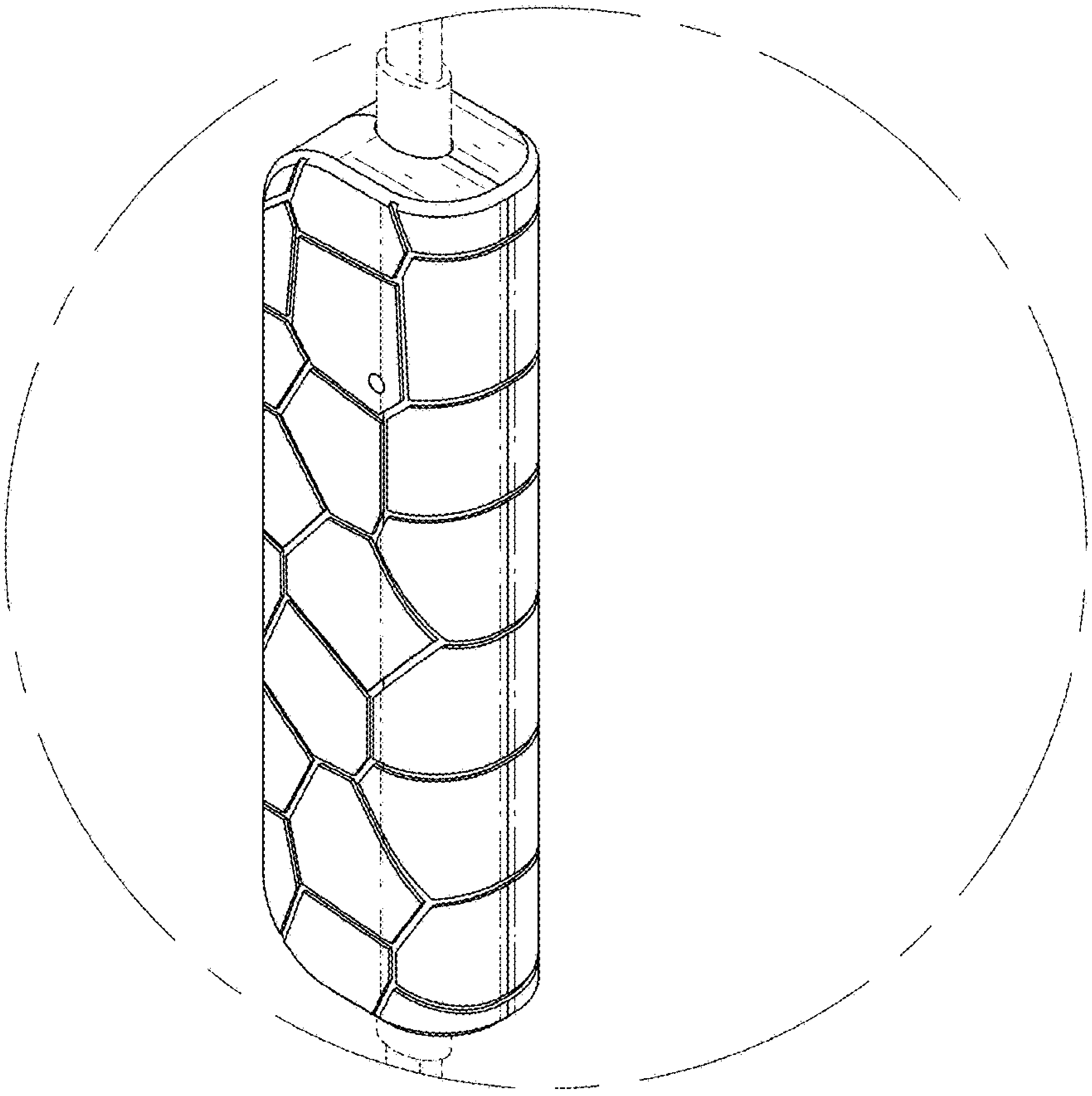


FIG. 11

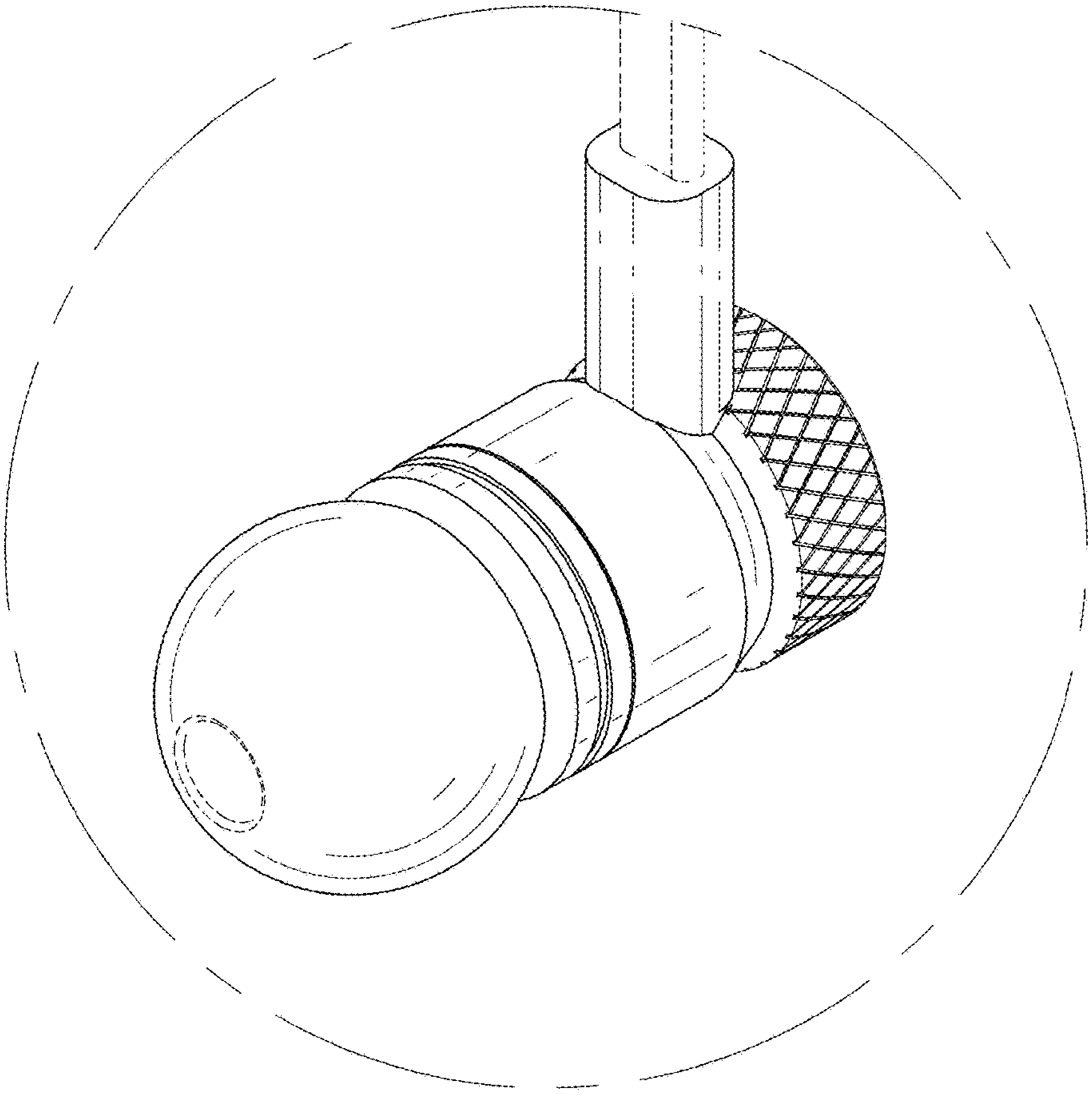


FIG. 12

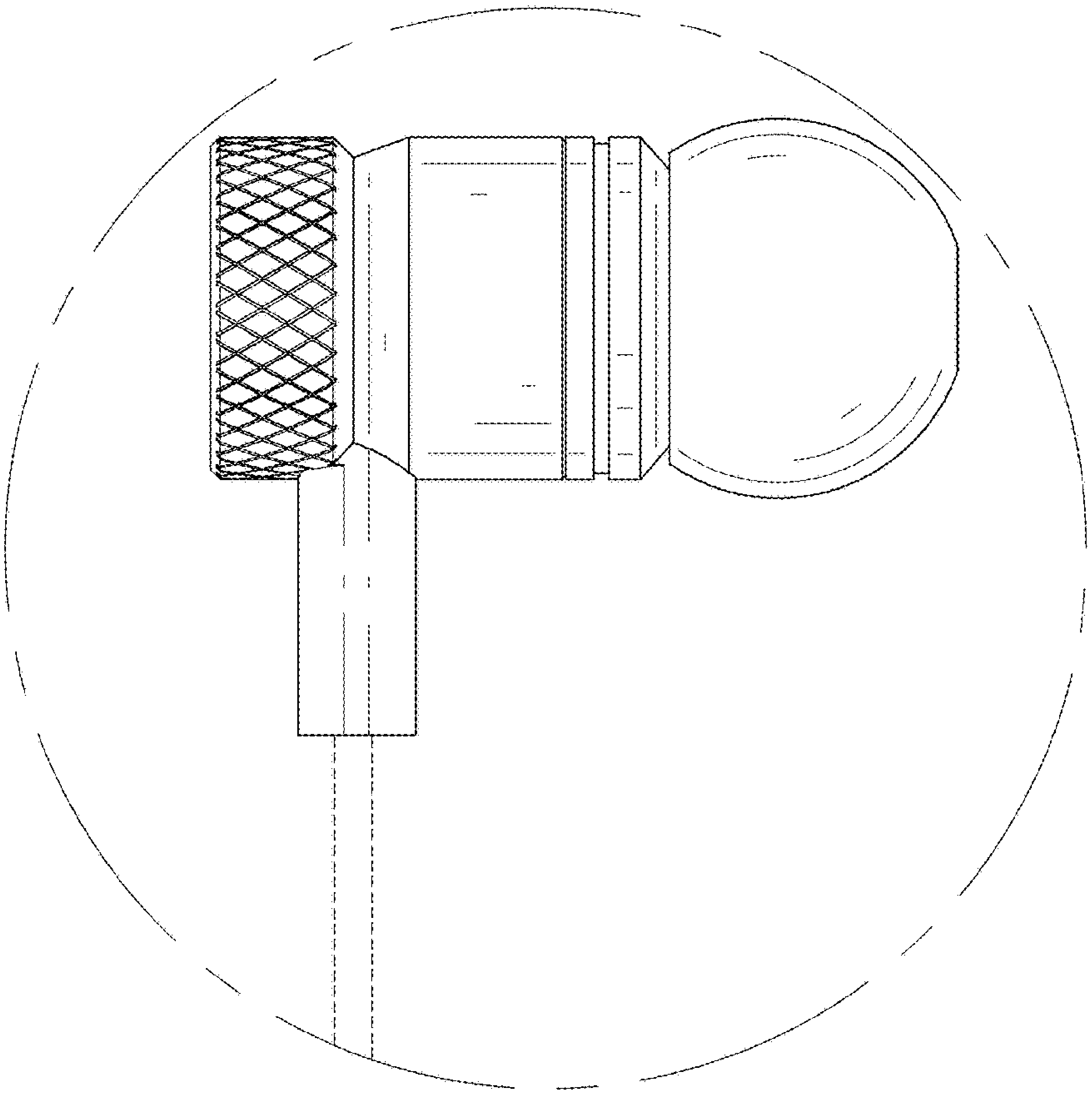


FIG. 13

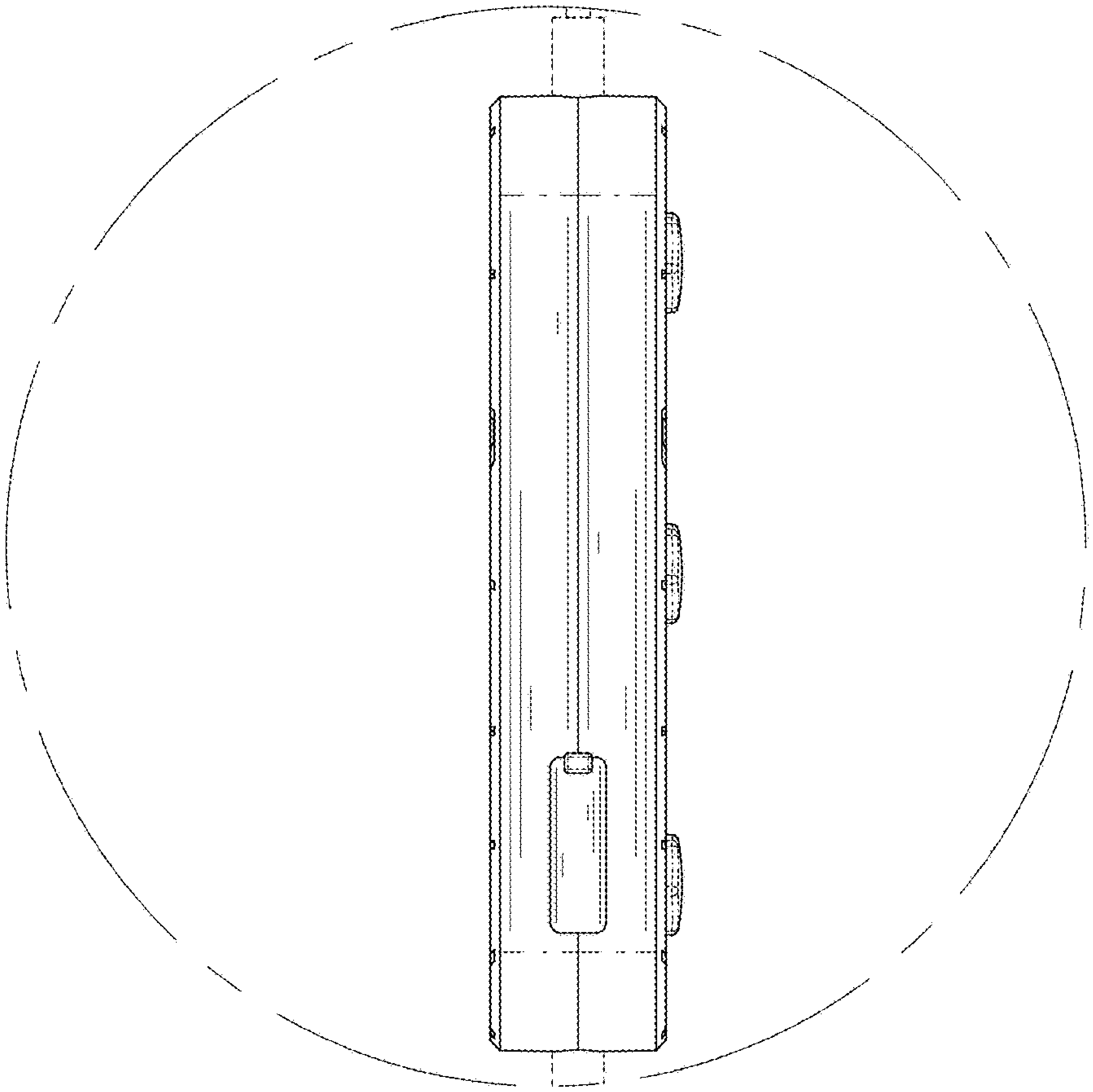
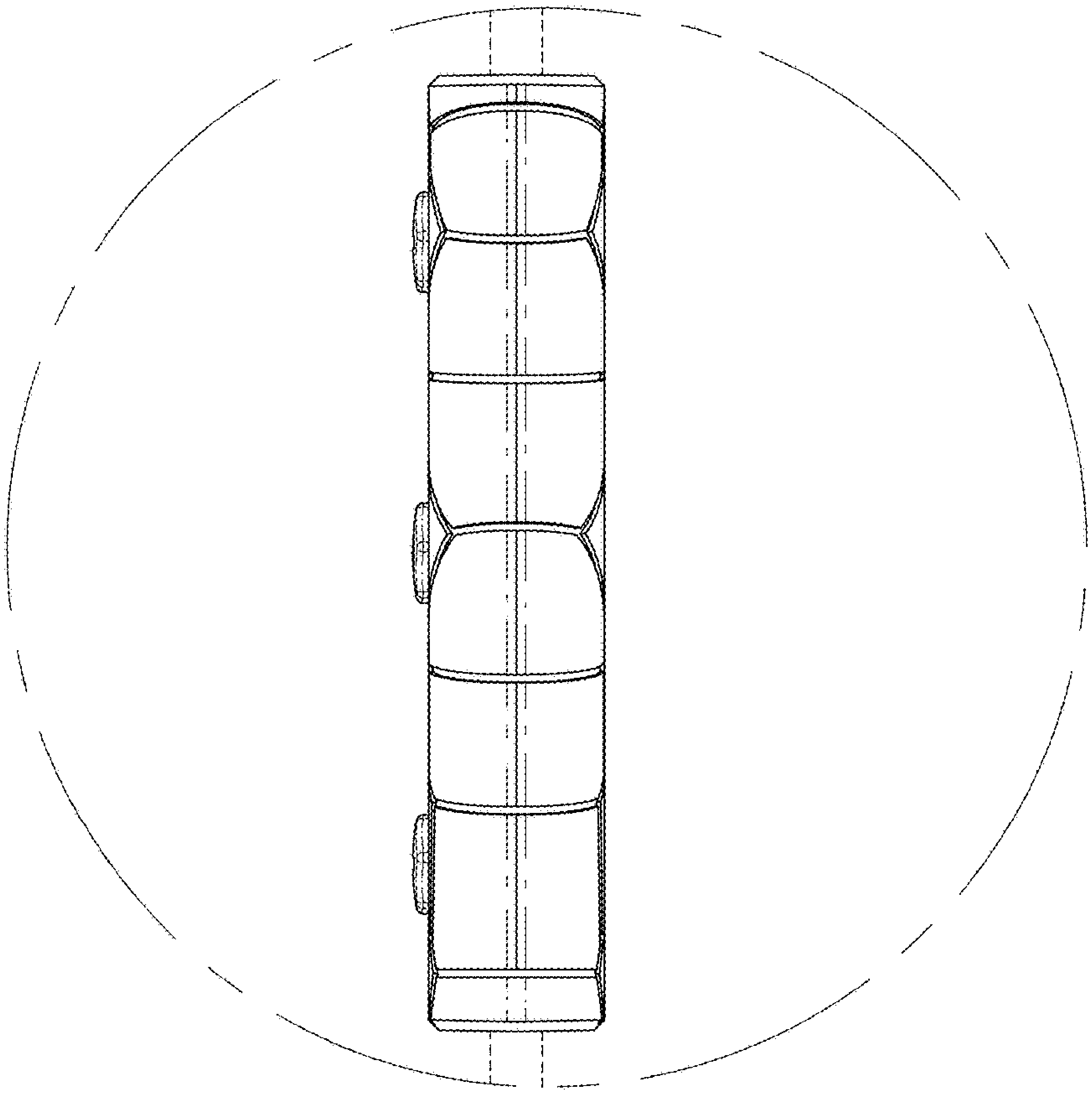


FIG. 14



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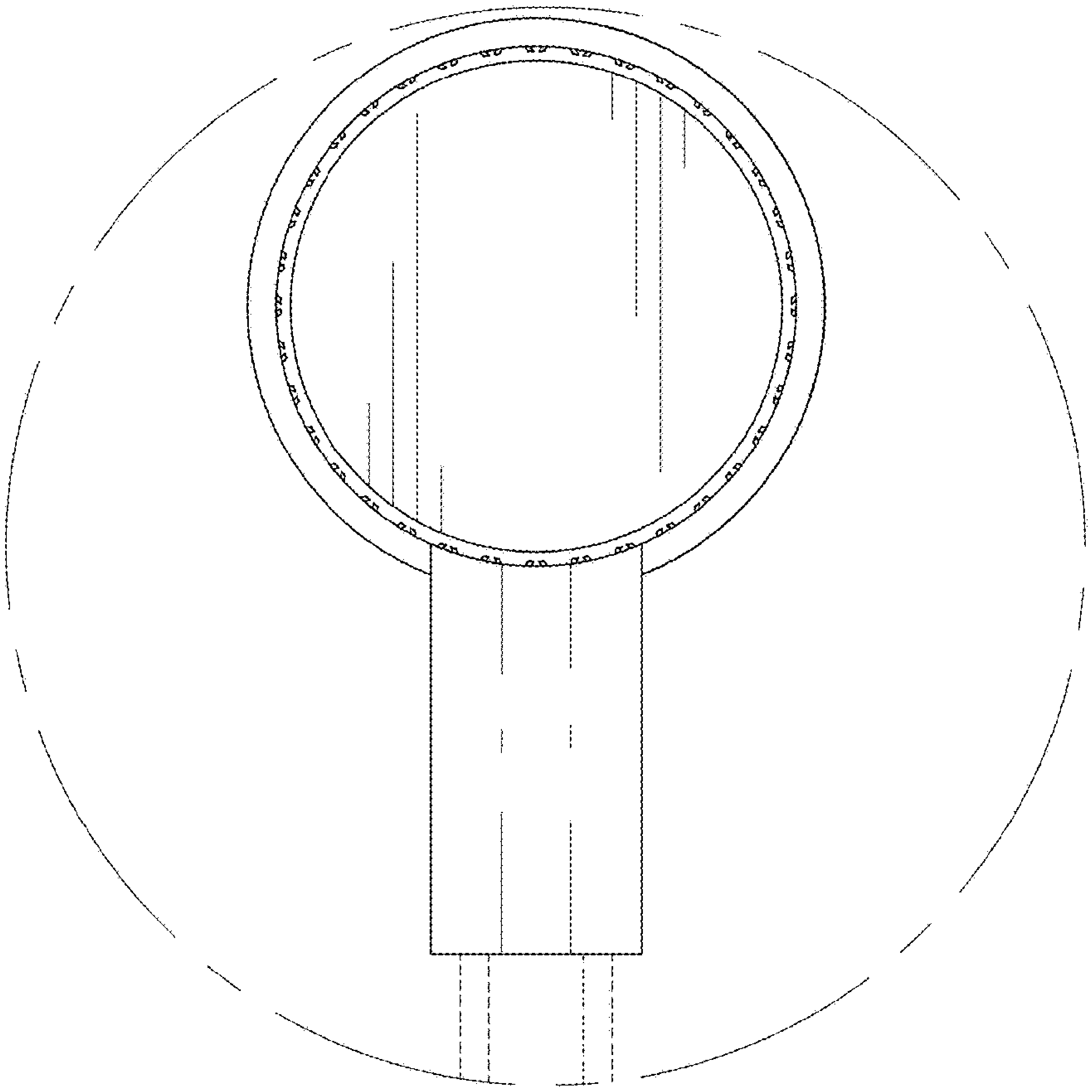

FIG. 16

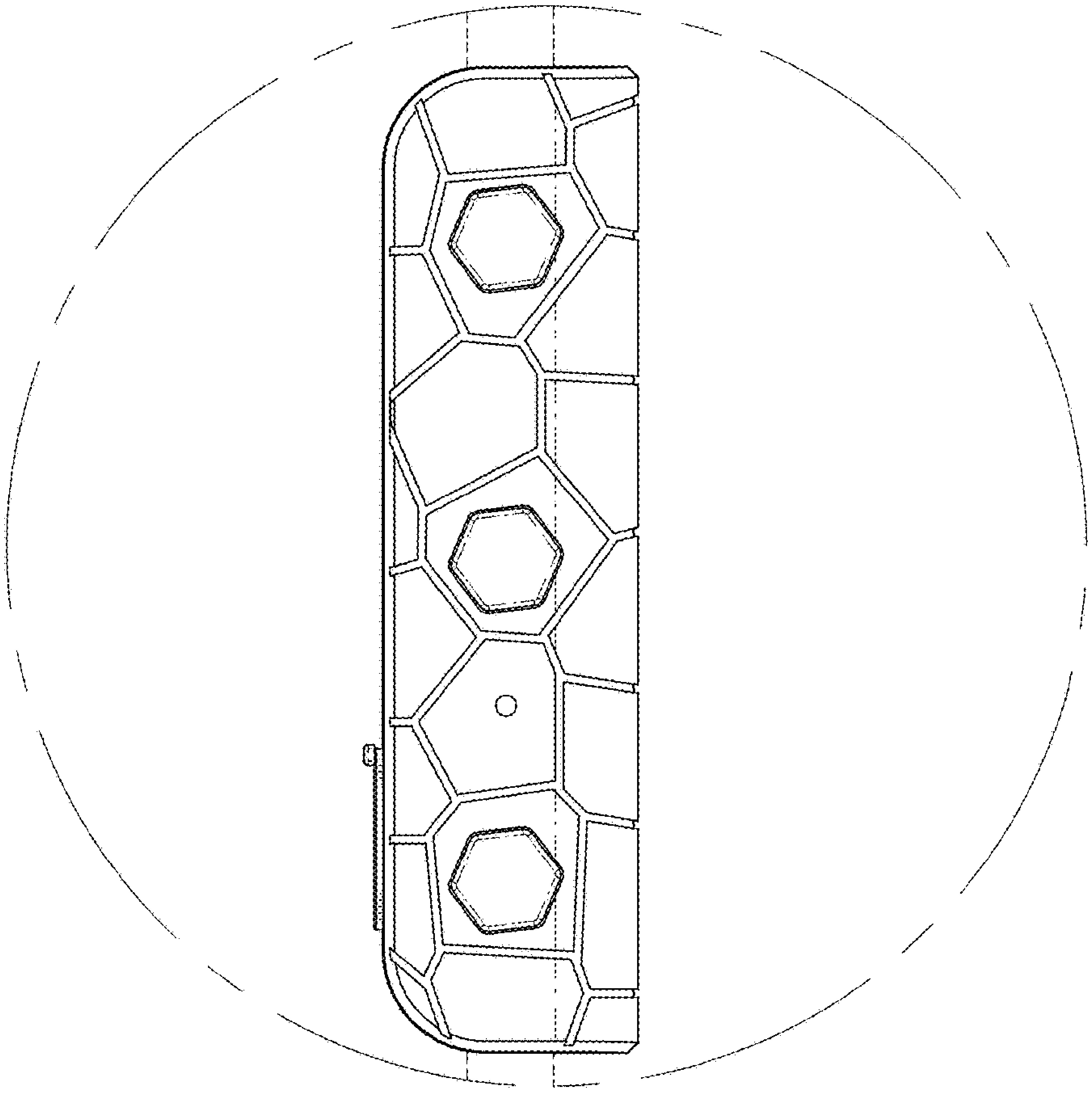

FIG. 17